Layer Stack Up Detail for: SAT0015A.PcbDoc

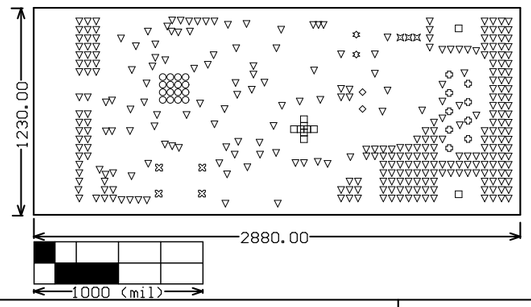
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil				
			12.6mil	FR-4	4.80	Core
GND	(.G1)	1.4mil				
			12.6mil	FR-4	4.80	PrePreg
Power	(.G2)	1.4mil				
			12.6mil	FR-4	4.80	Core
Bottom Layer	(.GBL)	1.4mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1230MIL X 2880MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 7 MIL
MIN. VIA PAD SIZE: 22 MIL
MINIMUM ANNULAR RING 0.15mm (6MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-4 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [ ] 62 MIL (1.12mm)+/-10% [X] OTHER 44.2 MIL
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.40MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.40MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG)
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S ID/LOGO: [ ] RAIL [X] METAL [ ] SILK



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	8	7.874mil (0.2mm)	PTH	Round
▽	316	10mil (0.254mm)	PTH	Round
○	16	12mil (0.305mm)	PTH	Round
⊠	3	19.685mil (0.5mm)	PTH	Round
☼	2	35.433mil (0.9mm)	NPTH	Round
◇	2	40mil (1.016mm)	PTH	Round
○	9	47.244mil (1.2mm)	PTH	Round
⊠	4	51.181mil (1.3mm)	PTH	Round
□	2	125.197mil (3.18mm)	PTH	Round
	362 Total			

Drill Table

TEXAS INSTRUMENTS

PROJECT TITLE: SAT0015_E2
DESIGNED FOR: Public Release
FILE NAME: SAT0015_E2.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0015	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ersion			
PLOT NAME = Fabrication Drawing	GENERATED : 1/21/2014 4:13:37 PM	TEXAS INSTRUMENTS	

ENGINEER:	LAYOUT BY:
Ajinder Singh	Krypton Solutions LLC
SCALE: 1.09	ALTIUM DESIGNER VERSION: 10.0.0.27009

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